Special Issue

New Advances in Memristors: Design and Applications

Message from the Guest Editor

Advances in memory technology, covering materials, device structures, and applications, signify a crucial shift in the landscape of modern computing. Material breakthroughs, including the development of innovative compounds and structures, have paved the way for next-generation memory devices. Simultaneously, improvements in memristor device architectures, such as crossbar arrays and 3D stacking, have expanded storage capacities and processing speeds. By vertically integrating multiple memory layers and emulating neural connections, these architectures optimize spatial efficiency, enhancing not only storage but also computation paradigms. These advancements have wide-ranging applications across industries, revolutionizing data storage and processing. As research continues to push the boundaries of possibilities, the future promises even more transformative innovations, reshaping the technological landscape and unlocking the frontiers of computing.

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Deadline for manuscript submissions

closed (30 June 2025)

Chips

an Open Access Journal by MDPI

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mdpi.com/si/203579

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Message from the Editor-in-Chief

Chips is a new journal with the aim to become a leading reference on all aspects of the IC domain. The journal is devoted to publishing rigorously peer-reviewed articles (such as original research, reviews, and communications) with the specific target to disseminate novelties in terms of research and knowledge as well as the most advanced state of the art on IC technologies, design, testing, and production. The journal offers the opportunity to actively spread new concepts and advancements in the IC domain and its increasing interrelated and multidisciplinary areas in a timely manner. More specifically, the journal will cover chip design, including CAD tools, chip production, and their wide spectrum of applications.

Editor-in-Chief

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